

**AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions, and listing of claims in the application:

**LISTING OF CLAIMS:**

Claims 1 - 2 (Cancelled).

Claim 3 (New): A white light LED comprising:

an electrode support structure;

an LED chip mounted to said electrode support structure for emitting light a first wavelength;

a phosphor layer overlaying said LED chip, said phosphor layer emitting light of a second wavelength responsive to being impinged by said light of said first wavelength, said emission of said first and second wavelengths being perceived as white light;

a light diffusion layer overlaying said phosphor layer to provide a substantially even distribution of said emissions of said first and second wavelengths; and,

an encapsulant molded over said electrode support structure and encasing said LED chip, said phosphor layer, and said light diffusion layer.

Claim 4 (New): The white light LED as recited in Claim 3, wherein said diffusion layer includes a plurality of transparent microparticles for refracting said emissions of said first and second wavelengths.

Claim 5 (New): The white light LED as recited in Claim 4, wherein said transparent microparticles are formed of one of an inorganic glass or a transparent polymeric material.

Claim 6 (New): The white light LED as recited in Claim 5, wherein said inorganic glass is a silicon dioxide glass.

Claim 7 (New): The white light LED as recited in Claim 5, wherein said polymeric material is selected from the group consisting of PMMA, PC, PE and PET.

Claim 8 (New): The white light LED as recited in Claim 3, wherein said diffusion layer includes  $\text{TiO}_2$ .

Claim 9 (New): The white light LED as recited in Claim , wherein said diffusion layer further includes  $\text{TiO}_2$ .

Claim 10 (New): A method of forming a white light LED, comprising the steps of:

- a. providing an electrode support structure;
- b. mounting an LED chip to said electrode support structure for emitting light of a first wavelength;
- c. providing a phosphor material that emits light of a second wavelength responsive to being impinged by said emission from said first wavelength;
- d. forming a layer of said phosphor material overlaying said LED chip;
- e. forming a light diffusion layer overlaying said phosphor material layer to provide a substantially even distribution of emissions from said LED chip and said phosphor material layer; and,
- f. molding an encapsulant over the structure from step e. to form an LED package.

Claim 11 (New): The method as recited in Claim 10, wherein the step of forming a light diffusion layer includes the step of forming a layer having a plurality of transparent microparticles therein for refracting said emissions from said LED chip and phosphor material layer.

Claim 12 (New): The method as recited in Claim 10, wherein the step of forming a light diffusion layer includes the step of forming a layer having  $\text{TiO}_2$  therein.

Claim 13 (New): The method as recited in Claim 11, wherein the step of forming a light diffusion layer further includes the step of adding  $\text{TiO}_2$  with said plurality of transparent microparticles.